

Notification#20180308001
Datasheet for TPS791
Information Only

Date: March 12, 2018
To: PREMIER FARNELL PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

Information Only Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPS79101DBVR	null
TPS79133DBVR	null
TPS79133DBVT	null
TPS79147DBVT	null
TPS79101DBVT	null
TPS79118DBVT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20180308001	PCN Date:	March 12, 2018
Title:	Datasheet for TPS791		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



TPS791

SLVS325D – MARCH 2001 – REVISED FEBRUARY 2018

Changes from Revision C (May 2002) to Revision D	Page
• Added <i>Device Information</i> table, <i>Simplified Schematic</i> figures to page 1, <i>ESD Ratings</i> table, <i>Thermal Information</i> table, <i>Pin Configuration and Functions</i> section, <i>Overview</i> section, <i>Feature Description</i> section, <i>Device Functional Modes</i> section, <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section	1
• Changed <i>TPS791xx</i> to <i>TPS791</i> throughout document	1
• Changed <i>Applications</i> section	1
• Changed <i>Description</i> section	1
• Deleted <i>Ordering Information</i> table	3
• Changed \overline{EN} pin description	3
• Added I/O data for GND pin	3
• Deleted <i>Package Dissipation Rating</i> table	3
• Changed V_I to V_{IN} , I_O to I_{OUT} , C_O to C_{OUT} , $C_{O(byp)}$ and $C_{(byp)}$ to C_{BYPASS} throughout document	3
• Changed formula in footnote 1 of <i>Recommended Operating Conditions</i> table	4
• Added V_{REF} parameter to <i>Electrical Characteristics</i> table	5
• Changed V_{CC} to V_{IN} in test conditions of <i>UVLO threshold</i> and <i>UVLO hysteresis</i> parameters	5
• Added $PSRR$ and V_{DO} symbols to <i>Power-supply ripple rejection</i> and <i>Dropout voltage</i> parameters	5
• Added conditions statement to <i>Typical Characteristics</i> section	6
• Changed I_{OUT} to C_{BYPASS} in <i>TPS79118 Output Spectral Noise Density vs Frequency</i> figure	7
• Changed I_{OUT} to C_{BYPASS} in <i>TPS79133 Output Spectral Noise Density vs Frequency</i> figure	7
• Changed third bullet in <i>Normal Operation</i> section	15
• Changed first bullet in <i>Disabled</i> section	15
• Changed V_{EN} column in <i>Device Functional Mode Comparison</i> table	15
• Added <i>active-low</i> to <i>Application Information</i> description	16

The datasheet number will be changing.

Device Family	Change From:	Change To:
TPS791	SLVS325C	SLVS325D

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/TPS791>

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

TPS79101DBVR	TPS79118DBVR	TPS79133DBVR	TPS79147DBVR
TPS79101DBVRG4	TPS79118DBVRG4	TPS79133DBVRG4	TPS79147DBVT
TPS79101DBVT	TPS79118DBVT	TPS79133DBVT	TPS79147DBVTG4
TPS79101DBVTG4	TPS79118DBVTG4	TPS79133DBVTG4	

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com